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Dr. Daniel Schmidt is a Manager and Senior Engineer at IBM Research in Albany, NY within IBM Semiconductors where he leads a team of engineers driving metrology developments for next generation semiconductor manufacturing. He is primarily focused on non-destructive dimensional and materials characterization using in-line optical and x-ray techniques. Daniel received his undergraduate degree in Microsystems Technology in Germany and earned a PhD in Electrical Engineering from the University of Nebraska-Lincoln in 2010. Prior to joining IBM Research in 2018, he was a Senior Research Fellow at the National University of Singapore and worked at GlobalFoundries leading metrology developments related to EUV lithography overlay and process characterization. Daniel has co-authored 110+ conference papers, 70+ journal articles, 20+ US patents and applications, and three book chapters. He is a guest lecturer at Rensselaer Polytechnic Institute and a guest editor for the Journal of Micro/Nanopatterning, Materials and Metrology. Daniel is a senior member at SPIE and serves as a committee member at the SPIE Advanced Lithography and Patterning Symposium as well as the International Conference on Spectroscopic Ellipsometry.